

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
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		DWN/CHK	DATE 07/28/2014	TIDA-00293 DLP 3D Printer MSTP Cape to Translator Cable		
		SYS ENGR				
	0314CP	MANU				
NHA	USED ON	QA		SIZE A	DRAWING NO 2514179	REV A
APPLICATION		APVD		SCALE NONE	SHEET 1 OF 3	

TIDA-00293 MSTP Cape to Translator Cable Assembly

1. Scope

The purpose of this document is to establish the assembly requirements for the cable between the BBB MSTP Cape and the logic level translator board used in TIDA-00293 DLP 3D Printer reference design.

2. Related Documents

3D Printer Level Translator Schematic

- ../Design Files/3D PRINTER LEVEL TRANSLATOR/3D Printer level translator schematic.pdf
- J3 (page 1)

BeagleBone MSTP Cape Schematic

- ../Design Files/BEAGLEBONE MSTP CAPE/BeagleBone MSTP Cape Schematic.pdf
- Red wired J8 Header GPIO pins (page 5)

3. Connections

Connect the following signals described below to connect the MSTP Cape to the 3D Printer Logic Level Translator board.

Connection	3D Printer Level Translator Board Connector	BBB MSTP Cape Connector
LCD_EN	2	1
LCD_RW	3	2
LCD_RS	4	3
LCD_BIT3	5	4
LCD_BIT2	6	5
LCD_BIT1	7	6
LCD_BIT0	8	7

4. Bill Of Materials

The following table lists the components necessary to construct the MSTP Cape to Translator cable.

Description	Manufacturer	Part Number	Qty
3D Printer Level Translator Board Connector	JST	EHR-8	1
3D Printer Level Translator Board Crimps	JST	SEH-001T-P0.6L	7
BBB MSTP Cape Connections	Sullins Connector Solutions	PREC040SAAN-RC (snap off 7 positions)	1

TIDA-00293 MSTP Cape to Translator Cable Assembly

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